

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/19/11393	
1.3 Title of PCN	MDmesh DM2 Technology 8" Wafer Front-end Capacity Extension - Ang Mo Kio (Singapore) - INDUSTRIAL	
1.4 Product Category	MDmesh DM2	
1.5 Issue date	2019-02-15	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Paolo PETRALI
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General	Wafer diameter modification	AMK Singapore

4. Description of change

	Old	New
4.1 Description	MDmesh DM2 Technology manufactured in the 6" wafer line of Ang Mo Kio (Singapore)	MDmesh DM2 Technology will be manufactured also in the 8" wafer line of Ang Mo Kio (Singapore)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Extension
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	by FG code and Q.A. number
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7. Timing / schedule

7.1 Date of qualification results	2019-02-14
7.2 Intended start of delivery	2019-05-14
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11393 Rel05-2019.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-02-15

9. Attachments (additional documentations)

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD11N60DM2	
	STD8N60DM2	
	STF11N60DM2	
	STP11N60DM2	
	STP18N60DM2	
	STP33N60DM2	
	STW56N60DM2	
	STW56N65DM2	
	STWA48N60DM2	
	STWA63N65DM2	

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